

# Plaskon NXG-1

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

## Message:

This material is an epoxy molding compound for high temperature, lead-free reflow. It is designed to withstand more demanding requirements in moisture performance, occasioned by the higher IR reflow temperatures required for processing lead-free packages. It is a highly filled, hybrid resin developed to pass JEDEC Level 2A at 260°C IR reflow temperature. It is a "green" compound with no halogens and a lower Tg than multifunctional materials.

General Information			
Features	Semi-conductive		
	Low (to no) lead content		
	Low hygroscopicity		
	Fast curing		
	Good formability		
	Heat resistance, high		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	2.00	g/cm <sup>3</sup>	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	2.55	MPa	ASTM D790
260°C	0.0686	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0125	MPa	ASTM D790
260°C	8.14E-4	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	140	°C	ASTM E1356
CLTE - Flow	8.9E-6	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Flammability	Nominal Value		Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			
Recommended Storage Temperature: <5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 6 months Life @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 2 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 0.5 days Spiral Flow, 175°C, 1000 psi: 140 cm Shimadzu Viscosity, 175°C, 1000 psi: 40 poise Ram Follower Gel Time, 175°C, 1000 psi: 18 sec Ash Content: 88.6 % Hydrolyzable Halides: <1 ppm Moisture Absorption, 85°C/85%RH, 168 hrs: 0.265% Cull Hot Hardness, Shore D: 75 All test specimens are transfer molded and post cured for 4 hours at 175°C Linear Thermal Expansion, Alpha 1: 8.9 cm <sup>-6</sup> /cm/°C Linear Thermal Expansion, Alpha 2: 36 cm <sup>-6</sup> /cm/°C			
Injection instructions			

Resin Transfer Molding:  
Molding Temperature: 165 to 185°C  
Molding Pressure: 1000 psi  
In Mold Cure Time: 50 to 100 sec  
Post Mold Cure Time, 175°C: 0 to 2 hr

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